PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3236828

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HEE CHEUL JUNG	04/30/2014
BO RAM I JANG	04/30/2014
JUN YONG PARK	04/30/2014
DAEWOONG SUH	04/30/2014

RECEIVING PARTY DATA

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City:	ANSAN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	425-851

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14355521

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ATTORNEY DOCKET NUMBER:	P5911US00
NAME OF SUBMITTER:	HAE-CHAN PARK
SIGNATURE:	/hae-chan park/
DATE SIGNED:	02/23/2015

Total Attachments: 4
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ASSIGNMENT SERVING AS DECLARATION PER 37 C.F.R. § 1.63(e)

As a below named inventor and Assignor, I declare that:

This assignment and declaration are directed to:

☒ The attached application entitled **LIGHT-EMITTING DIODE PACKAGE AND METHOD FOR MANUFACTURING SAME** having attorney docket number P5911US00 ("Application"), which is the national stage entry of PCT/KR2012/008153, filed on October 9, 2012, and which claims priority from:
Korean Patent Application No. 10-2011-0112025, filed October 31, 2011.

☐ As amended on ________________________ (if applicable);

The above-identified Application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the Application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in the Application,

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Seoul Viosys Co., Ltd.
1B-36, 727-5, Wonsi-dong,
Danwon-gu, Ansan-si
Gyeonggi-do 425-851
Republic of Korea

Seoul Viosys Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Inventor and Assignor has hereunto set hand and seal.

First Inventor's and Assignor's Name: Hee Cheul JUNG

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Date: 2014. 4. 30

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Second Inventor's and Assignor's Signature: ______________________

Date: ______________________

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Third Inventor's and Assignor's Signature: Boram-i Jang

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Fourth Inventor's and Assignor's Signature: Jun Yong PARK.

Date: 2014. 4. 30

Docket No. P5911US00

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Fifth Inventor's and Assignor's Signature:

Date: April 30th, 2014